

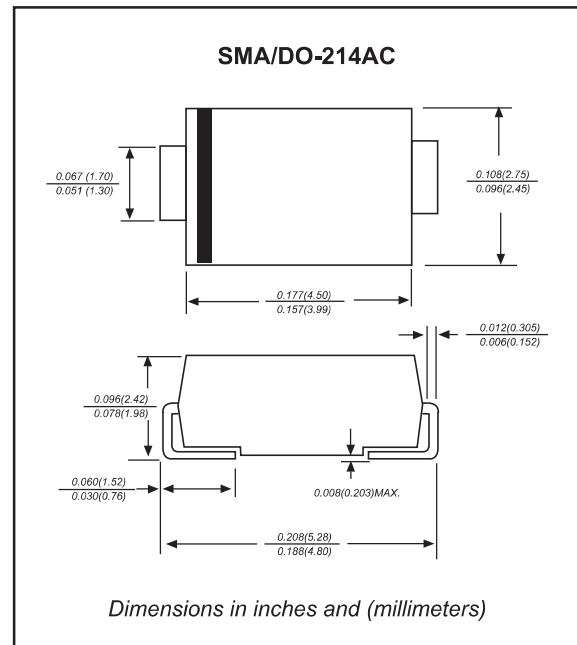
### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 260°C/10 seconds at terminals
- ◆ Compliant to RoHS 2.0
- ◆ Compliant to Halogen-free

### Mechanical data

- ◆ **Case:** JEDEC DO-214AC molded plastic body
- ◆ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Color band denotes cathode end
- ◆ **Mounting Position:** Any

### Package outline



### Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

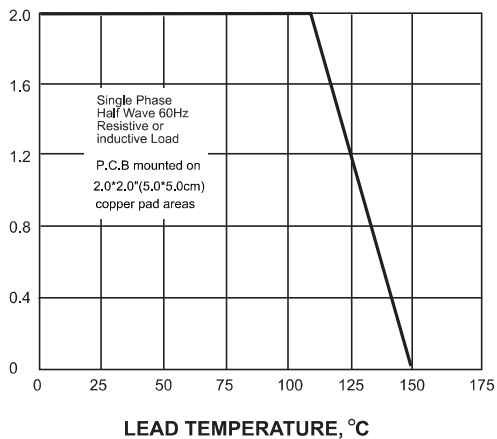
PARAMETER	SYMBOLS	B220A	B230A	B240A	B250A	B260A	B280A	B2100A	B2150A	B2200A	UNITS	
Maximum repetitive peak reverse voltage	$V_{RRM}$	20	30	40	50	60	80	100	150	200	V	
Maximum RMS voltage	$V_{RMS}$	14	21	28	35	42	56	70	105	140	V	
Maximum DC blocking voltage	$V_{DC}$	20	30	40	50	60	80	100	150	200	V	
Maximum average forward rectified current at $T_L$ (see fig.1)	$I_{AV}$	2.0									A	
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	50.0									A	
Maximum instantaneous forward voltage at 2.0A	$V_F$	0.50		0.70		0.85		0.95			V	
Maximum DC reverse current at rated DC blocking voltage	$I_R$	0.5			10.0			0.1		2.0		mA
Typical junction capacitance (NOTE 1)	$C_J$	220									pF	
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	80									$^\circ\text{C}/\text{W}$	
Operating junction temperature range	$T_J$	-55 to +150									$^\circ\text{C}$	
Storage temperature range	$T_{STG}$	-55 to +150									$^\circ\text{C}$	

**Note:** 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
 2. P.C.B. mounted with 2.0x2.0" (5.0x5.0cm) copper pad areas

### Rating and characteristic curves

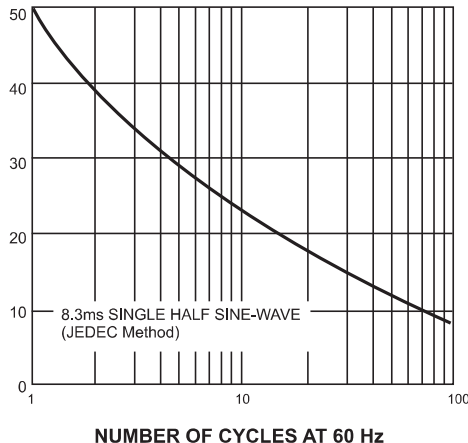
AVERAGE FORWARD RECTIFIED CURRENT, AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



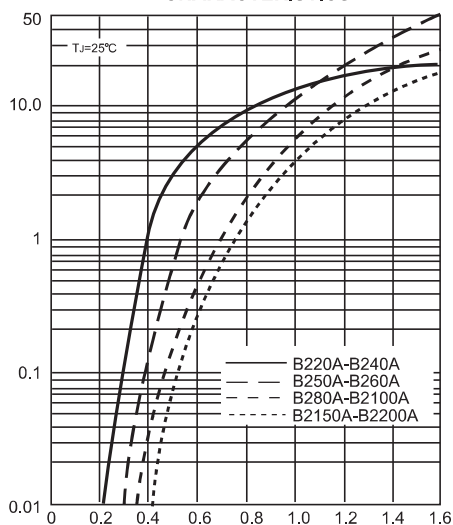
PEAK FORWARD SURGE CURRENT, AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



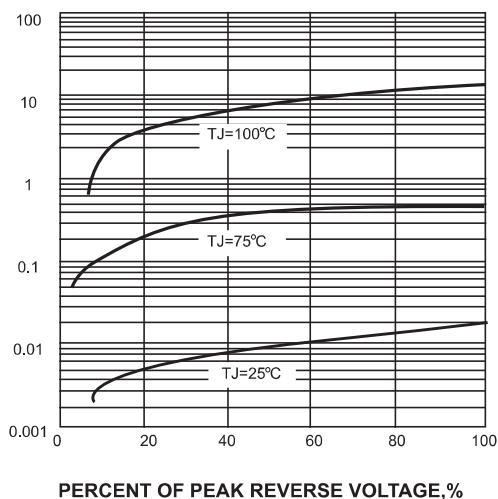
INSTANTANEOUS FORWARD CURRENT, AMPERES

FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



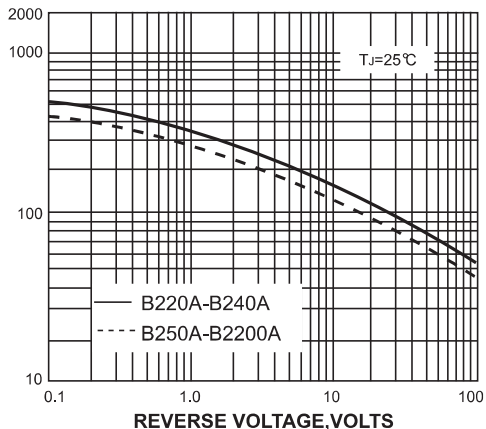
INSTANTANEOUS REVERSE CURRENT, MILLIAMPERES

FIG. 4-TYPICAL REVERSE CHARACTERISTICS



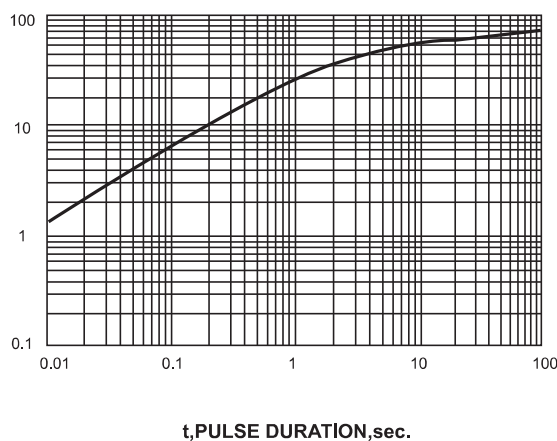
JUNCTION CAPACITANCE, pF

FIG. 5-TYPICAL JUNCTION CAPACITANCE





TRANSIENT THERMAL IMPEDANCE, °C/W

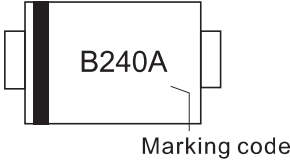
FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



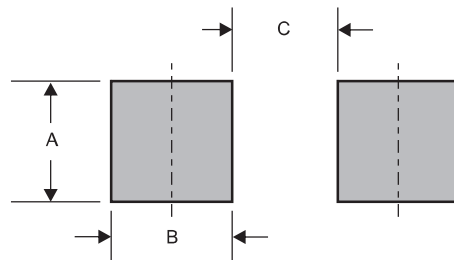
**Pinning information**

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

**Marking**

Type number	Marking code	Example
B220A	B220A	
B230A	B230A	
B240A	B240A	
B250A	B250A	
B260A	B260A	
B280A	B280A	
B2100A	B2100A	
B2150A	B2150A	
B2200A	B2200A	

**Suggested solder pad layout**

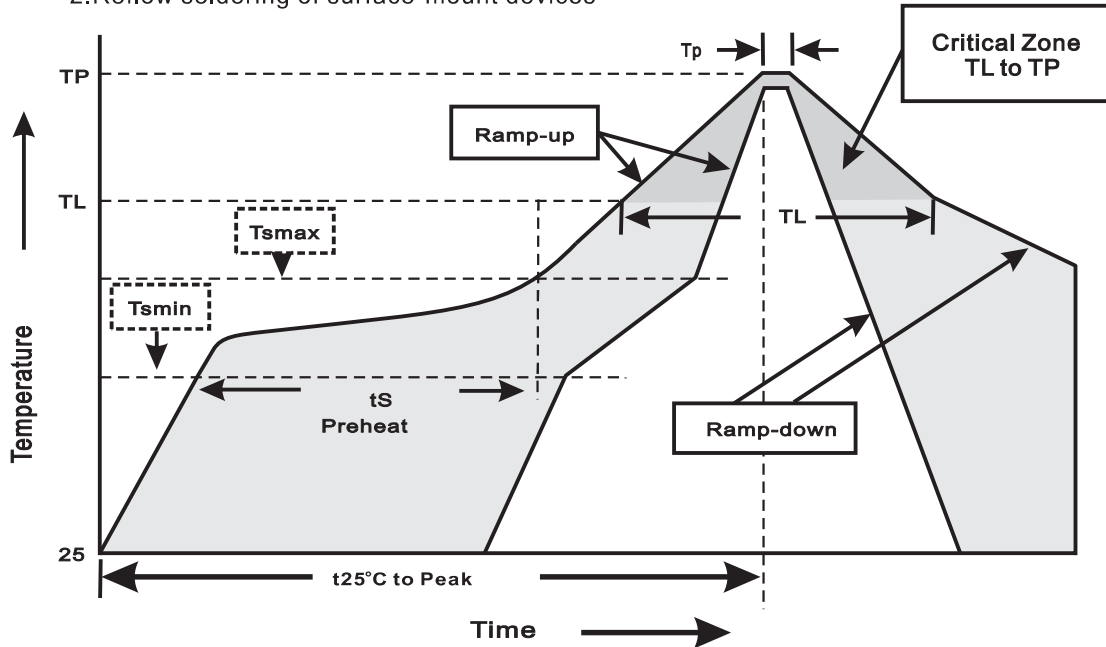


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMA	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)

**Suggested thermal profiles for soldering processes**

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T <sub>L</sub> to T <sub>P</sub> )	<3°C/sec
Preheat -Temperature Min(T <sub>smin</sub> ) -Temperature Max(T <sub>smax</sub> ) -Time(min to max)(t <sub>s</sub> )	150°C 200°C 60~120sec
T <sub>smax</sub> to T <sub>L</sub> -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T <sub>L</sub> ) -Time(t <sub>L</sub> )	217°C 60~260sec
Peak Temperature(T <sub>P</sub> )	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t <sub>p</sub> )	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes